



DEFENSE LOGISTICS AGENCY
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IN REPLY
REFER TO

DSCC-VAC (Mr. Barone/DSN 850-0510 / (614)692-0510)

MEMORANDUM FOR VSS (Mr. Art Hudson)

SUBJECT: Dated Engineering Practices (EP) Study on Test Method 2073, Visual Inspection for Die
(Semiconductor Diode) - Project Number: 5961- 0197

Findings and recommendations Engineering Practices (EP) Study, dated 30 July 2001, and
attachments are enclosed.

It is requested that your office take the necessary electronic action to reflect completion of these
projects.

Enclosure

TOM HESS
Chief
Active Devices Team



ENGINEERING PRACTICES STUDY

TITLE: Problems in the Standardization of Visual Inspection
For Die Testing

30 July 2001

STUDY PROJECT (SEE ATTACHMENT 1)

FINAL REPORT

Study Conducted by JC-13.1 task group

Prepared by

Alan Barone

- I. OBJECTIVE: The objective of this study is to improve test method 2073, Visual Inspection for Die (Semiconductor Diode).
- II. BACKGROUND: A JEDEC JC-13.1 task group was formed to study this issue due to the test method not being performed correctly and missing important criteria.
- III. RESULTS: Test method 2073 was revised to include front side and backside visual requirements, and the addition of descriptive figures. See attached method below.
- IV. CONCLUSION: Test method 2073 was improved.
- V. RECOMMENDATIONS: This method must be incorporated into the next draft of MIL-STD-750.



2073.1.pdf